

**ABSTRACT OF THE DISCLOSURE**

In substrate packaging and mounting, such as for a flip chip mounted on a thin-core or coreless substrate, a high degree of rigidity and support is imparted to the substrate, to overcome bending/flexing/distortion during mounting/packaging of the chip and to prevent possible

- 5 chip damage, by a stiffener. Such a stiffener may be of one or multiple pieces in any suitable shape/form to allow its non-interfering positioning on the substrate, and made by any suitable process of any suitable material, including conductive material and material capable of withstanding the temperatures of chip mounting/bonding operations. Such a stiffener prevents bending/flexing/distortion of thin-core and coreless substrate arrangements during
- 10 mounting/interconnection processes to achieve thinner and more light-weight electronics specifically afforded by thin-core/coreless substrate arrangements while lowering manufacturing time/costs.